Sheet 1 of 1	Sheet	1	of	1
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Form PTO-1449 US Dept. of Commerce (REV. 8-83) PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 116753			APPLICATION NO. 10/630,862						
INFO	RMATI	ON DISCLOSURE STATEMENT									
(Use several sheets if necessary) APPLICANT(S)											
Masahiro KOJIMA et al.											
NOV 2 2 2005 %				FILING DATE July 31, 2003			GROUP 1754				
PATENT DOCUMENTS											
EXAMINER INITIAL	<u> </u>	DOCUMENT NUMBER		DATE	NAME		CLASS	SUB CLASS			
CC	1	6,809,042	10/2	26/2004	KOJIMA et al.		<u> </u>				
	2	U.S. Pub. No. 2004/0110641	6/1	0/2004	KOJIMA et al.						
	3	5,180,707	1/1	9/1993	GAO et al.						
	4	4,968,664	11/0	6/1990	SUGIHAVA et al.						
CC	5	U.S. Pub. No. 2005/0170969	8/4/	/2005	KOJIMA et al.						
FOREIGN PATENT DOCUMENTS											
		DOCUMENT NUMBER	DATE		COUNTRY		CLASS	SUB CLASS			
CC	6	JP 2004-026625 (with Abstract and machine translation)	1/29/2004		JAPAN						
	7	JP 06-318412 (with Abstract and machine translation)	11/15/1994		JAPAN						
	8	JP 02-199023 (with Abstract)	8/7/	/1990	JAPAN						
	9	DE 203 15 783	2/26/2004		GERMANY						
	10	EP 0 412 199	2/13/1991		EUROPE						
CL	11	WO 92/13649	8/2	0/1992	WIPO						
		OTHER DOCUMENTS (In	cludir	ng Author,	Title, Date, Pertinent Pages, etc.)						
CC	12	K. Ohbayashi et al., "High-T _c (95 K) As-Grown Superconducting Bi-Sr-Ca-Cu-O Thin Films", Japanese Journal of Applied Physics, Part 2 (Letters), Vol. 29, No. 11, pages L2049-L2052, November 1990									
	 										
CL	13	N. H. Sinh, "Properties of the Bi-Surpl Magnetic Materials, Vol. 262, No. 3, p	lus Su pages	uperconduct 514-519, J	ting Bi _{2.1-x} Pb _x Sr ₂ Ca ₂ Cu ₃ O _y Compour une 2003	ds", Jou	umal of Mag	netism and			
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EXAMINER Blue P. Cook DATE CONSIDERED S/11/06											
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.											

Date: November 22, 2005